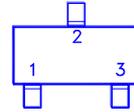
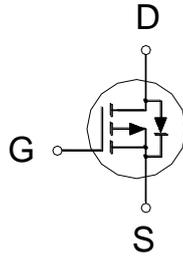


PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
-20V	100mΩ	-3A



1: GATE
2: DRAIN
3: SOURCE



ABSOLUTE MAXIMUM RATINGS ($T_A = 25\text{ °C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Drain-Source Voltage		V_{DS}	-20	V
Gate-Source Voltage		V_{GS}	±8	V
Continuous Drain Current	$T_A = 25\text{ °C}$	I_D	-3	A
	$T_A = 70\text{ °C}$		-2.4	
Pulsed Drain Current ¹		I_{DM}	-20	
Power Dissipation	$T_A = 25\text{ °C}$	P_D	0.9	W
	$T_A = 70\text{ °C}$		0.6	
Junction & Storage Temperature Range		T_J, T_{stg}	-55 to 150	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Ambient ²	$R_{\theta JA}$		130	°C / W

¹limited by maximum junction temperature.

²The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25\text{ °C}$.

ELECTRICAL CHARACTERISTICS ($T_J = 25\text{ °C}$, Unless Otherwise Noted)

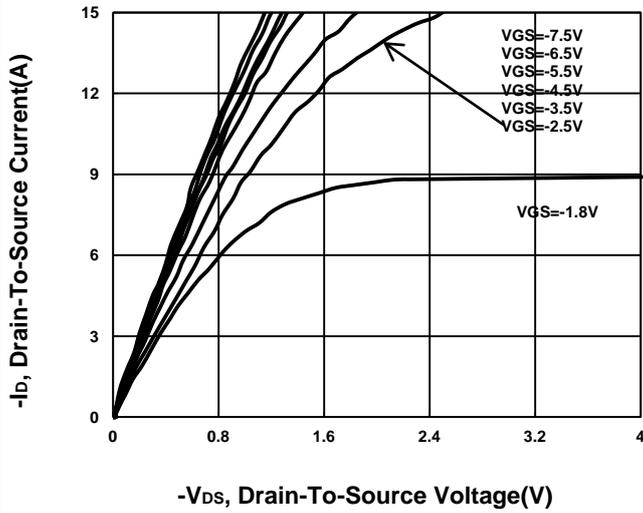
PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = -250\mu A$	-20			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\mu A$	-0.3	-0.5	-1	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 8V$			±100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -16V, V_{GS} = 0V$			-1	μA
		$V_{DS} = -10V, V_{GS} = 0V, T_J = 70\text{ °C}$			-10	
Drain-Source On-State Resistance ¹	$R_{DS(on)}$	$V_{GS} = -1.8V, I_D = -1A$		140	190	mΩ
		$V_{GS} = -2.5V, I_D = -2A$		109	130	
		$V_{GS} = -4.5V, I_D = -2.5A$		80	100	
On-State Drain Current ¹	$I_{D(ON)}$	$V_{DS} = -5V, V_{GS} = -4.5V$	-20			A
Forward Transconductance ¹	g_{fs}	$V_{DS} = -5V, I_D = -2.5A$		8.1		S

DYNAMIC						
Input Capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = -10V, f = 1MHz$		434		pF
Output Capacitance	C_{oss}			56		
Reverse Transfer Capacitance	C_{rss}			54		
Total Gate Charge ²	Q_g	$V_{DS} = -10V,$ $I_D = -2.5A, V_{GS} = -4.5V$		6.3		nC
Gate-Source Charge ²	Q_{gs}			0.7		
Gate-Drain Charge ²	Q_{gd}			2		
Turn-On Delay Time ²	$t_{d(on)}$	$V_{DS} = -10V$ $I_D \cong -2.5 A, V_{GS} = -4.5V, R_{GEN} = 6\Omega$		9.4		nS
Rise Time ²	t_r			38		
Turn-Off Delay Time ²	$t_{d(off)}$			60		
Fall Time ²	t_f			66		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_J = 25^\circ C$)						
Continuous Current	I_S				-3	A
Forward Voltage ¹	V_{SD}	$I_F = -2.5A, V_{GS} = 0V$			-1.2	V
Reverse Recovery Time	t_{rr}	$I_F = -2.5A, di_F/dt = 100A / \mu S$		11		nS
Reverse Recovery Charge	Q_{rr}				3	

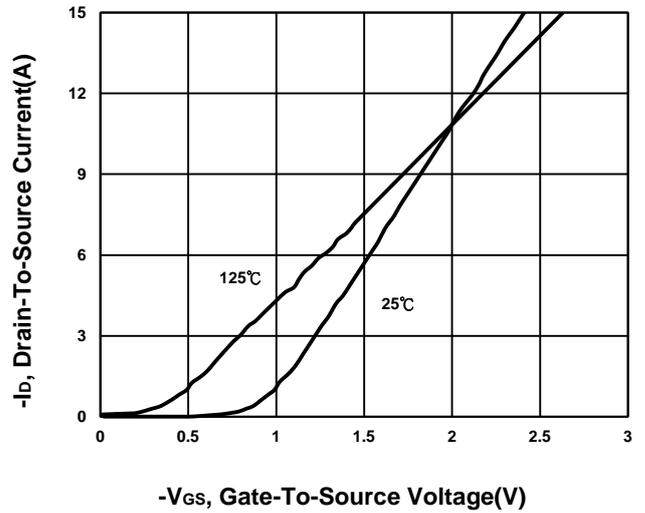
¹Pulse test : Pulse Width $\leq 300 \mu sec$, Duty Cycle $\leq 2\%$.

²Independent of operating temperature.

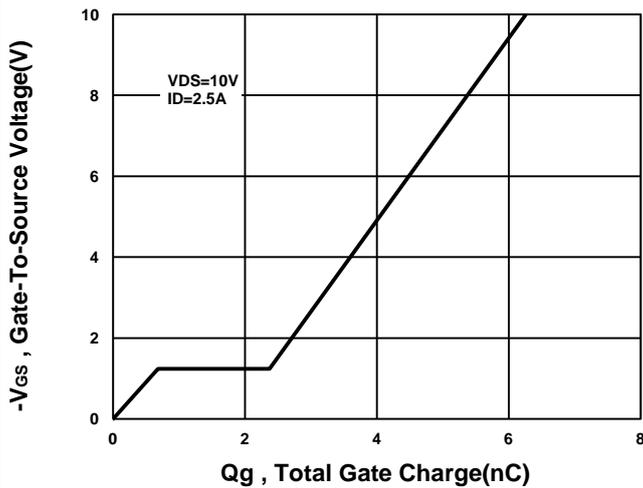
Output Characteristics



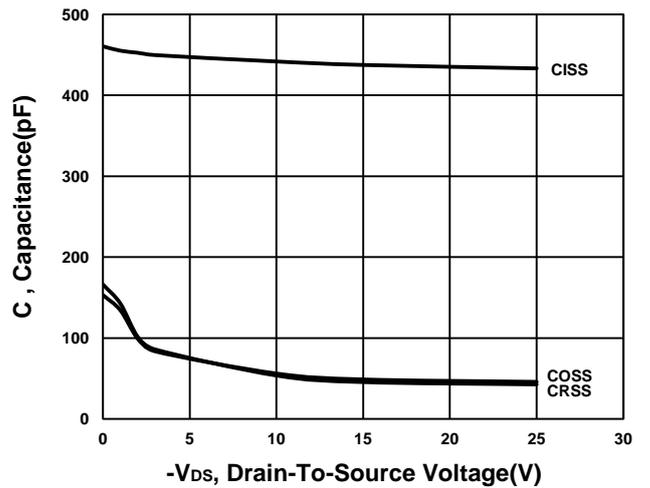
Transfer Characteristics



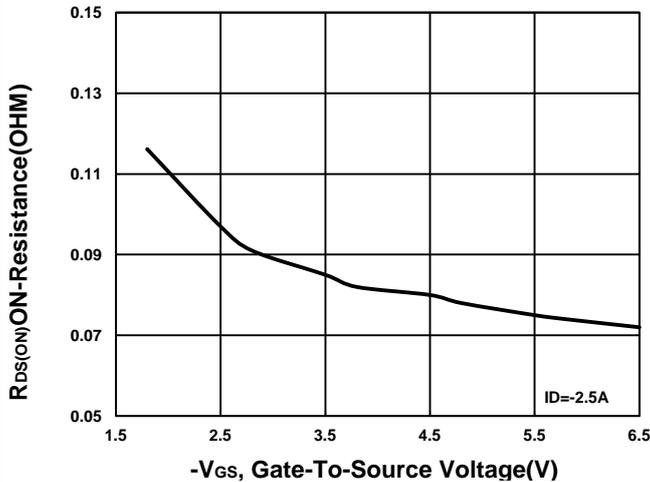
Gate charge Characteristics



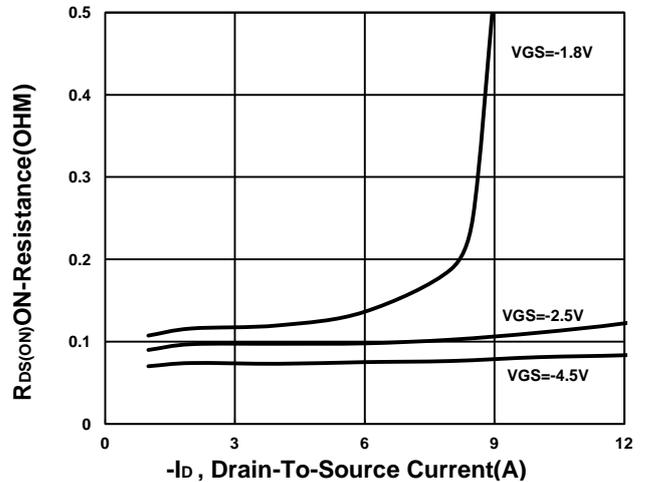
Capacitance Characteristic



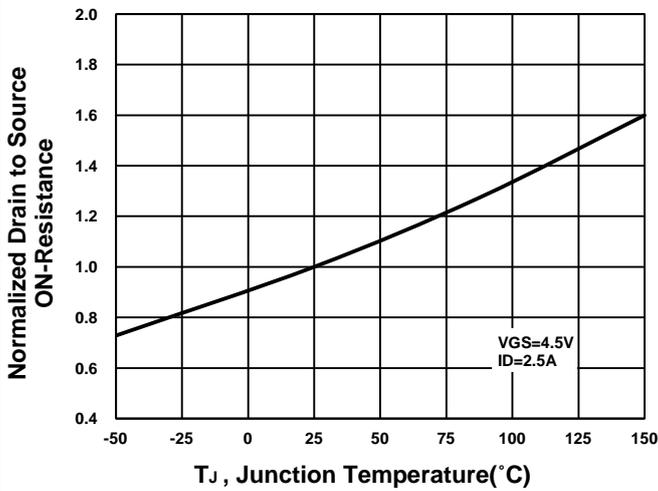
On-Resistance VS Gate-To-Source



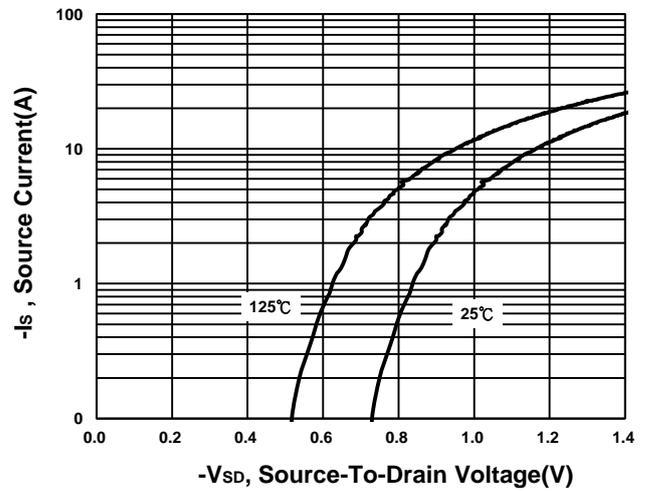
On-Resistance VS Drain Current



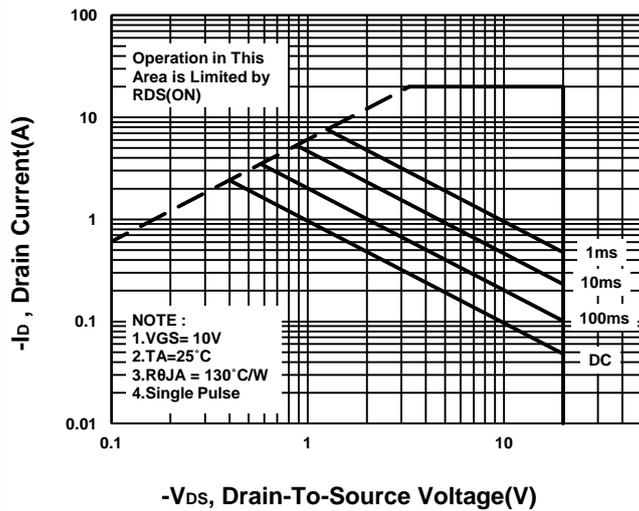
On-Resistance VS Temperature



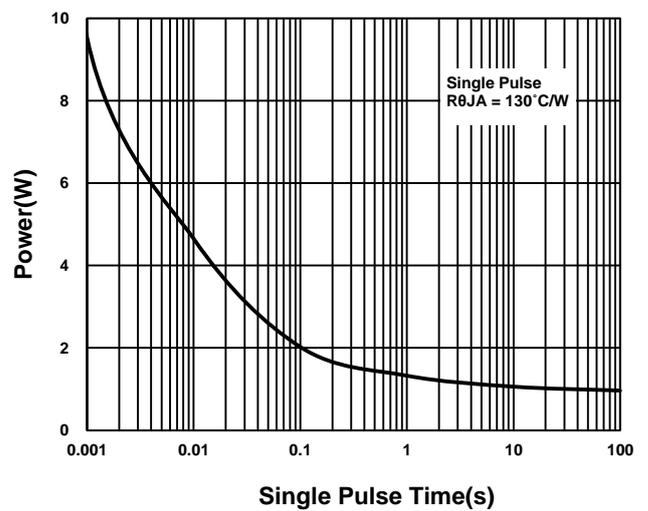
Source-Drain Diode Forward Voltage



Safe Operating Area



Single Pulse Maximum Power Dissipation



Transient Thermal Response Curve

